Doc. No.: NR060511E

May 11, 2006

Constructing a new production factory for semiconductor manufacturing equipment: Increasing wafer cleaning equipment production capacity starting from November

May 11, 2006: The Semiconductor Equipment Company (President: Takashige Suetake) of Dainippon Screen Mfg. Co., Ltd. (Headquarters: Kyoto, Japan), recently initiated construction of a new semiconductor equipment factory to be known as Fab.FC-2, within SCREEN's existing Hikone plant (480-1 Takamiya-cho, Hikone, Shiga). The factory is expected to start operations by November 2006.

The continued expansion of the market for digital home appliances and memory cards is complemented by increased demand for personal computers and portable telephones in emerging countries. All this is helping to maintain the growth of the semiconductor industry, and levels of semiconductor device manufacturing plant investment are expected to remain high as a result. Equipment manufacturers supporting the semiconductor industry recognize that market demand continues to create an urgent need for increased production.

The current situation in the industry, paired with SCREEN's superior reputation as a manufacturer of cleaning equipment for 300 mm wafers – a field in which SCREEN boasts the top share worldwide – are the background for the construction of the new Fab.FC-2 factory. This factory will increase production capacity for wafer cleaning equipment, including batch wafer cleaning equipment, and will be the SCREEN corporate group's fourth semiconductor manufacturing equipment production site. The new construction will take place within SCREEN's existing Hikone plant, adjacent to the Fab.FC-1 factory, which was established in the year 2001. Because the new factory will share both basic design concepts and certain production facilities with the older factory, it should be completed remarkably quickly. The new Fab.FC-2 factory will immediately double production capacity (as compared with current Fab.FC-1 production capacity) allowing for a more stable supply of production equipment that will support the long-term, continued prosperity of semiconductor device manufacturers. The new factory is also being constructed with the long-term goal of enabling production of manufacturing equipment for the next-generation 450 mm size wafers that are expected to be used in semiconductor fabrication in the future.

The construction of the Fab.FC-2 factory will expand the company's wafer cleaning – including batch wafer cleaning – equipment production capacity. It will increase SCREEN's competitiveness and help the company further increase its market share in the semiconductor equipment industry.

Artist's rendition of completed Fab.FC-2 Factory
Please download the photo from
http://www.screen.co.jp/press/nr-photo/indexE.html

< New Factory Overview >

Name:	Hikone Plant Fab.FC-2 "Fab." implies Fabulous or Fabricate; "FC" is Fine Cleaning, which is used in the product label for the FC-3100 300 millimeter wafer cleaning unit. SCREEN is working towards next-generation implementation of production management control that utilizes information technology (IT).
Location:	480-1 Takamiya-cho, Hikone, Shiga
Size of Site:	Approximately 5,600 square meters
Building Footprint:	Approximately 5,200 square meters
Floor Space:	Approximately 9,000 square meters
Building Type:	Steel reinforced structure, 3 floors
Cost:	Approximately 2.7 Billion Yen
Start:	April 2006
Completion:	November 2006
Intended Use:	Production of wafer cleaning equipment (batch type cleaning equipment, single-wafer cleaning equipment, etc.)